

BB02-NN :- 1.27mm X 1.27mm (0.05" X 0.05") BOX HEADER, SMD, DUAL ROW - 10 TO 80 CONTACTS

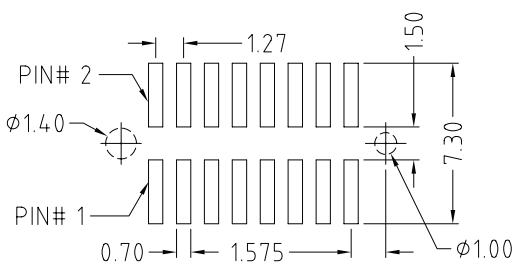
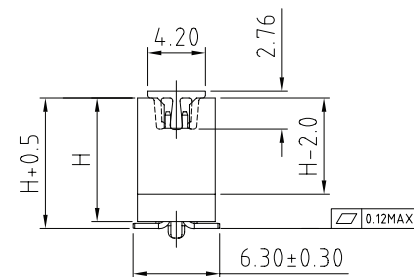
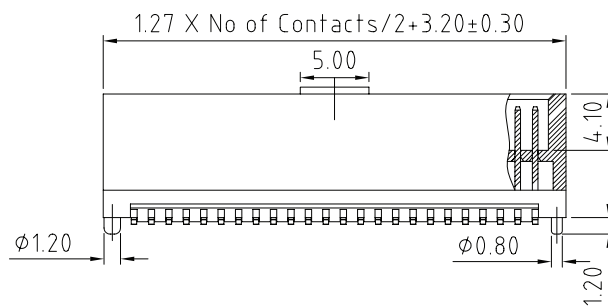
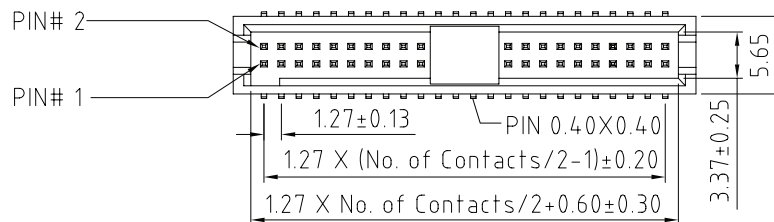
SPECIFICATIONS :

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	AC 300 V
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0
	STANDARD : LCP
PLATING	GOLD OR TIN OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC
	WAVE: 250°C FOR 5-10 SEC
	MANUAL SOLDER: 380°C FOR 3-5 SEC

MATES WITH: BB02-CL
BB02-CM
BB02-CN
BB02-CQ
BB02-CR
BB02-CU

NOTE 1: INSULATOR AND MATING HEIGHT INFORMATION

INSULATOR HEIGHT	MATING HEIGHT
A=9.0MM	5.4MM+SOCKET HEIGHT
B=9.6MM	6.0MM+SOCKET HEIGHT
C=10.2MM	6.6MM+SOCKET HEIGHT
D=10.7MM	7.1MM+SOCKET HEIGHT
E=11.0MM	7.4MM+SOCKET HEIGHT
F=11.5MM	7.9MM+SOCKET HEIGHT
G=12.2MM	8.6MM+SOCKET HEIGHT
H=13.5MM	9.9MM+SOCKET HEIGHT
J=14.2MM	10.6MM+SOCKET HEIGHT
K=15.2MM	11.6MM+SOCKET HEIGHT
L=17.6MM	14.0MM+SOCKET HEIGHT
M=18.6MM	15.0MM+SOCKET HEIGHT

RECOMMENDED PC BOARD SMD LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER

B B 0 2 - N N X X 1 - X X X - X 0 0 0 0 0

NO. OF CONTACTS
10 TO 80

CONTACT PLATING OPTIONS

K = GOLD FLASH (STANDARD)
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TIN

INSULATION
HEIGHT "H"
(SEE NOTE 1)

PACKAGING OPTIONS

3 - TUBE
5 - TUBE & CAP
6 - T & R
8 - T & R & CAP

WITH / WITHOUT
LOCATING PEG
A = WITH
B = WITHOUT

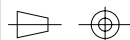
Scale: 2.5:1

Drawn: CHC

App'd: XXXX

Date: 26 NOV '09

THIRD ANGLE



Title BOX HEADER

Revision: 1.0

Unstated Tolerances:

X. ± 0.30
X. ± 0.25
XX ± 0.15
XXX ± 0.10

Material

SEE NOTE

NOT TO SCALE

UNIT: mm



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Type: BB02-NN

BB02-NN

Drawing Number:

Sheet 1 of 1

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